

REDCUBE HIGH POWER TERMINALS

TODAY'S SPEAKERS



PRESENTATION
Stephan Bächle
Field Application Engineer



MODERATION

Markus Eberle

Marketing Department

INFORMATION ABOUT THE WEBINAR

You are muted during the webinar.

However, you can ask us questions using the chat function.

Duration of the presentation 30 Min

Q&A: 10 – 15 Min

Any questions?

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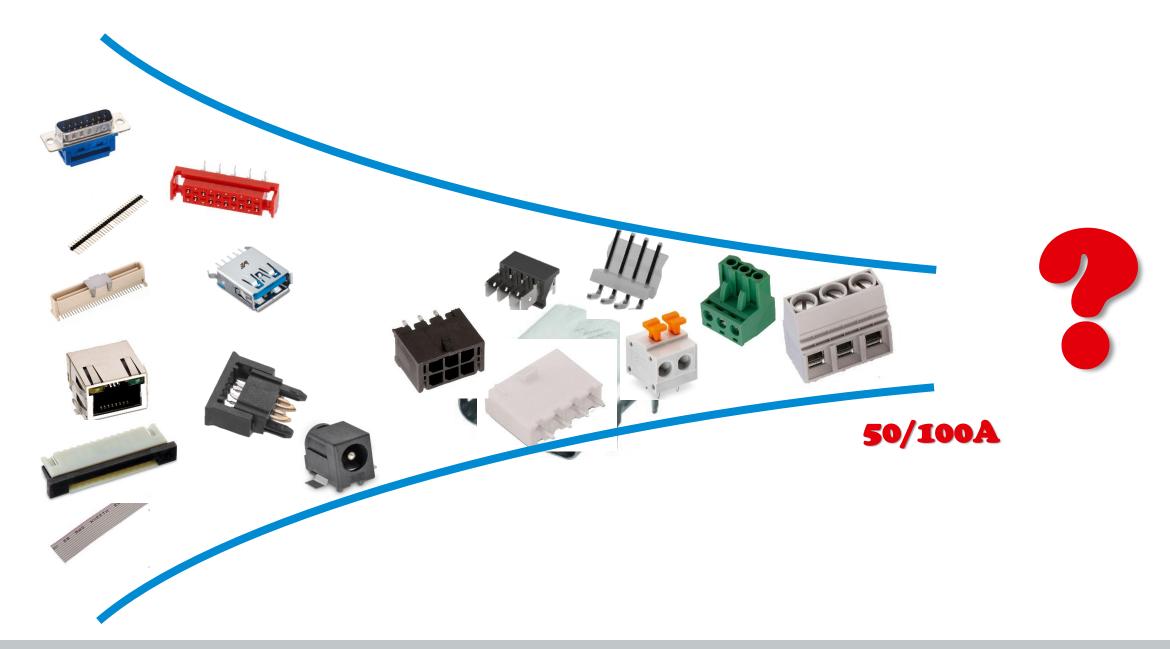
Please help us to optimize our webinars!

We are looking forward to your feedback.

On our channel Würth Elektronik Group

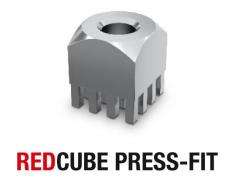
And on <u>Digital WE Days 2023 YouTube Playlist</u>







RED CUBE GLOBAL RANGE

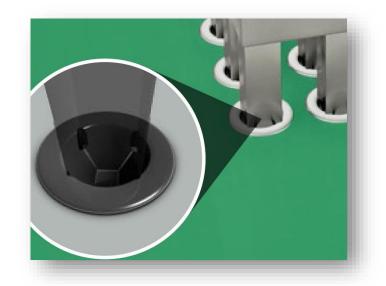


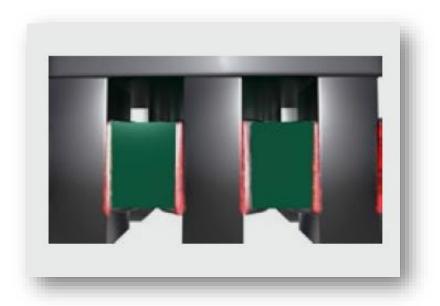






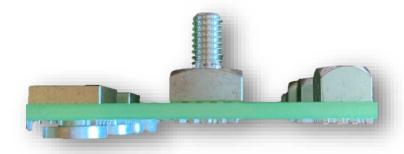






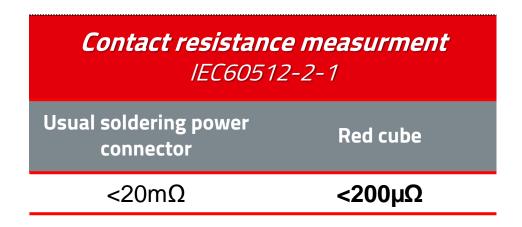
- > solder free
- gastight
- Powerful electrical connection

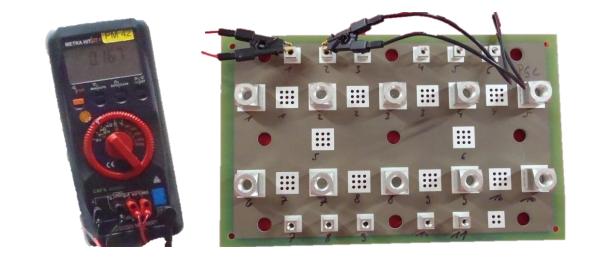






HOW THIS IS CERTIFIED: ELECTRICAL

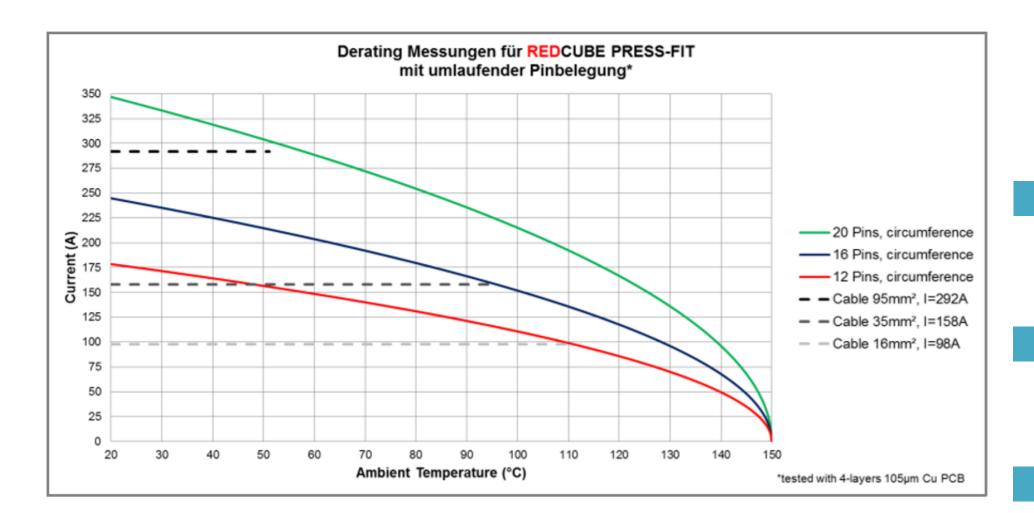




>Less contact resistance leads to less temperature rise



DERATING CURVES





2 rows



Circumference

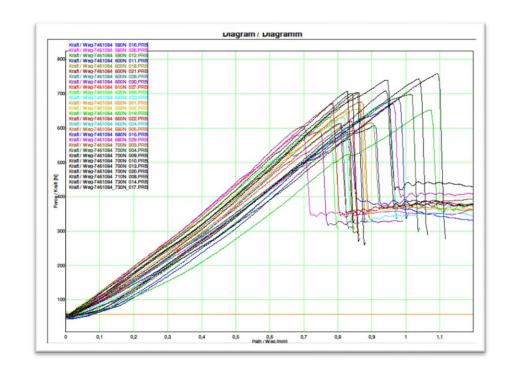


Full

HOW THIS IS CERTIFIED: MECHANICAL

Pull-out test







Extraction effort **10kg / pin** with PCB 1,6mm

HOW THIS IS CERTIFIED: MECHANICAL

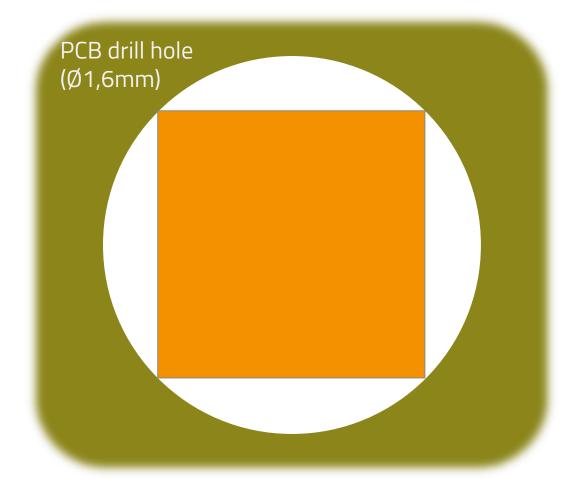
Pull-out test



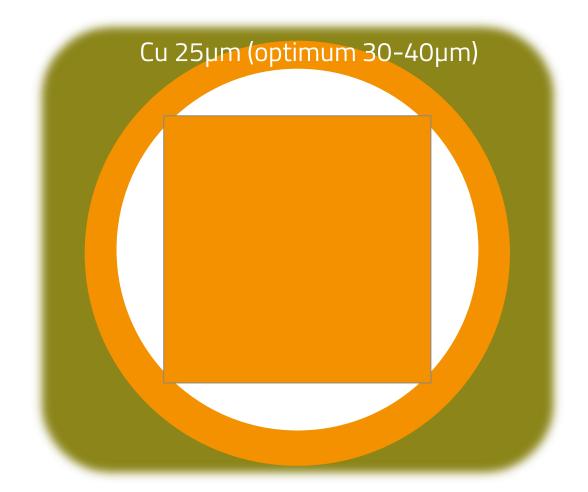




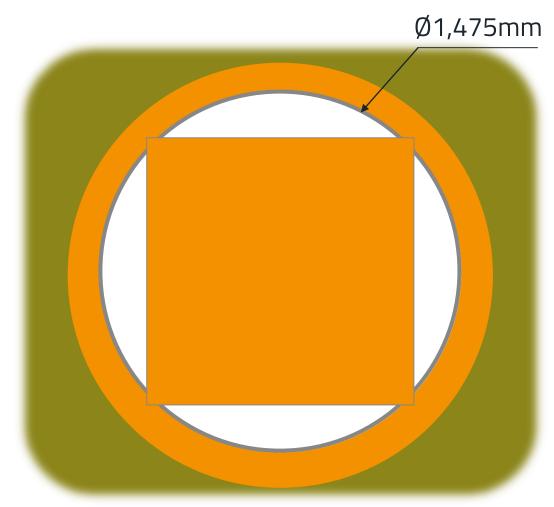




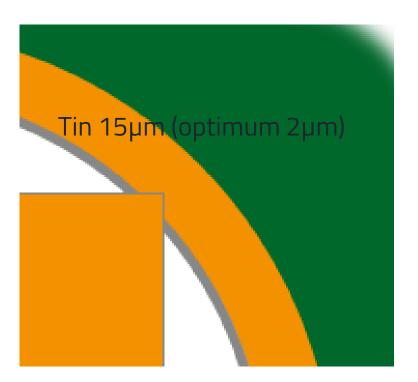


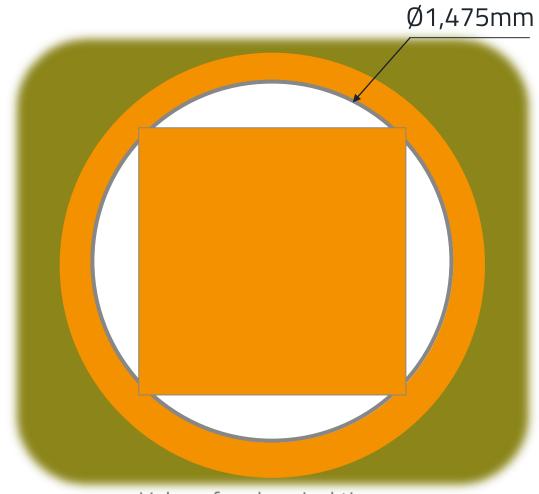




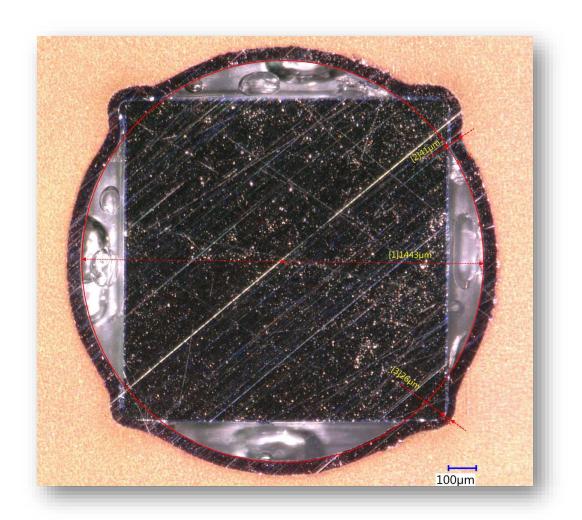


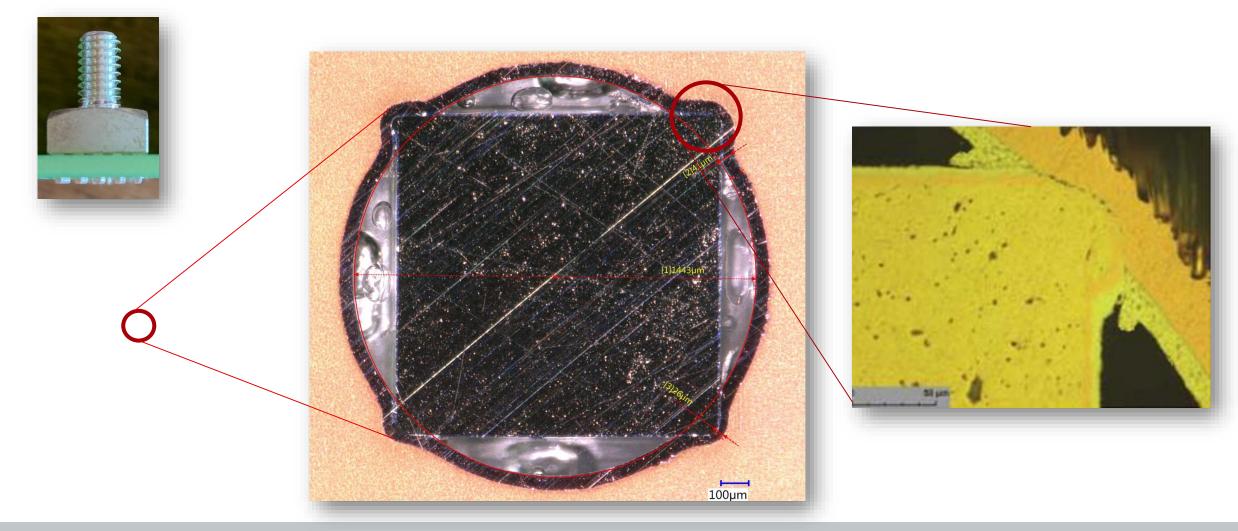
Values for chemical tin



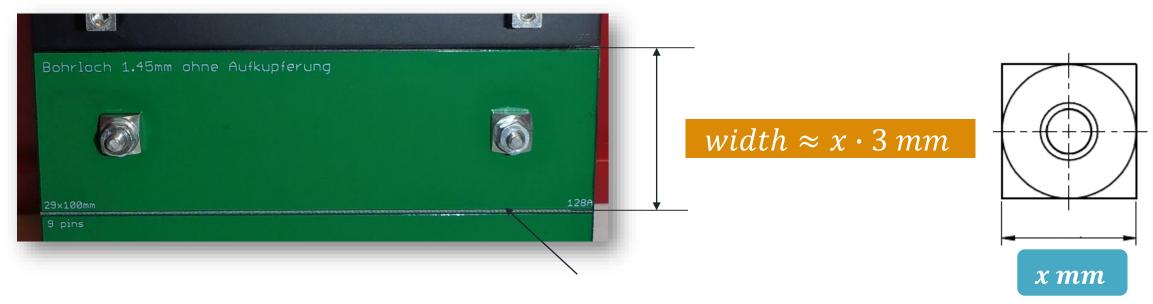






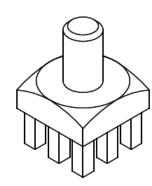


DESIGN A POWER PCB WITH RED CUBE: RULE OF THUMB



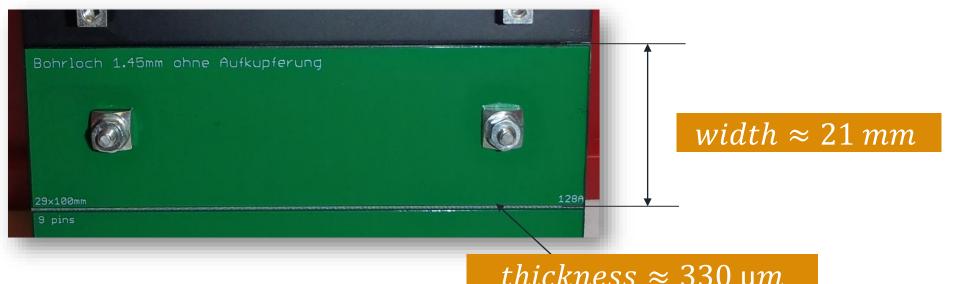


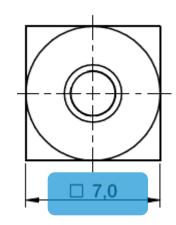
Properties	Test conditions		Value	Unit	Tol.
Rated Current	@ 20 °C	I _R	I	Α	max.





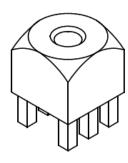
DESIGN A POWER PCB WITH RED CUBE: SOME TIPS





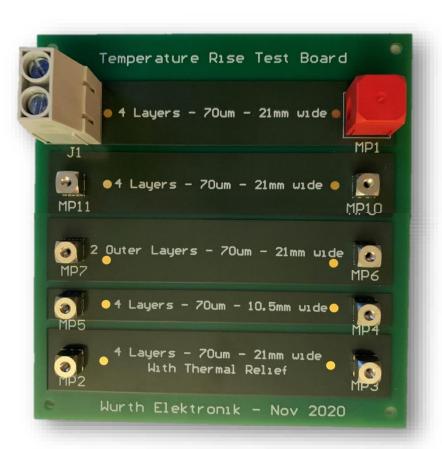
thickness $\approx 330 \,\mu m$ 4 or 5 layers of $70 \,\mu m$ or
3 layers of $105 \,\mu m$

Properties	Test conditions		Value	Unit	Tol.
Rated Current	@ 20 °C	I_{R}	100	А	max.



Test goal:

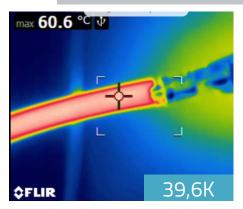
- Heat repartition
- Verify trace design
- Nb of layers influence

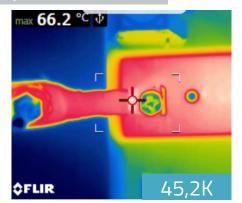


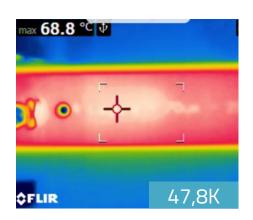
Working current 100A 4 layers 70µm 21mm wide Ambient Temp = 21°C

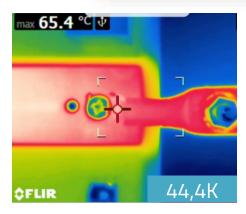






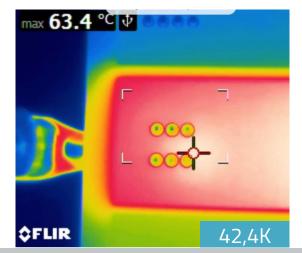








Bottom view







Working current 100A





in the full system

Bottom view \$FLIR 42,4K



• 4 Layers - 70um - 21mm wide • 📧

MP10

Working current 100A Temperature Rise Test Board 45K 59K 63K 4 Layers - 70um - 21mm wide MP1 40K 45K •4 Layers - 70um - 21mm wide • MP11 MPLO Working current 100A 44K 55K 2 Outer Layers - 70um - 21mm wide MP7 MP6 62K ● 4 Layers - 70um - 10.5mm wide 47K MP5 4 Layers - 70um - 21mm wide With Thermal Relief Wurth Elektronik - Nov 2020



Work

- Redcube is
 - small
 - high current
 - cooling down PCBs

Work

- Rule of thumb high current design is a good approach
- Always check temperature with prototype test

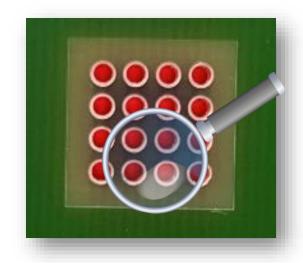




PRESS-FIT PROCESS

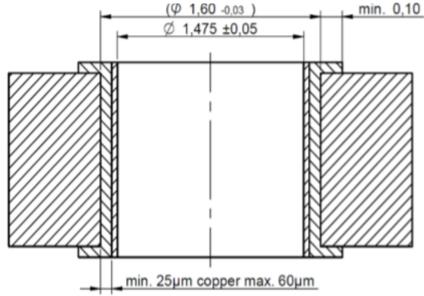
- Materiel needed:
 - PCB
 - Support
 - Base
 - Stamp
 - Press



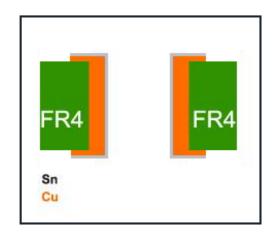


Chemical tin

ENIG (NiAu)

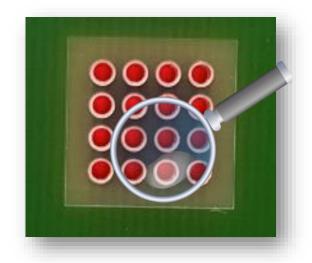


- > 25 60µm Copper optimum 30-40µm
- max. 15µm Tin optimum 2µm



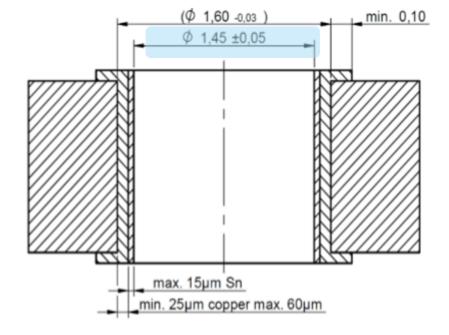


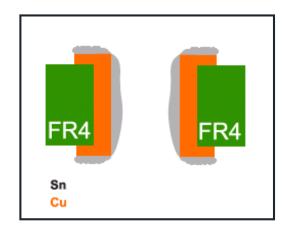


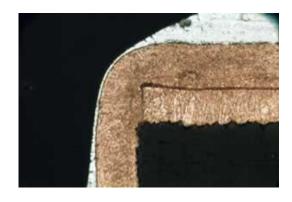


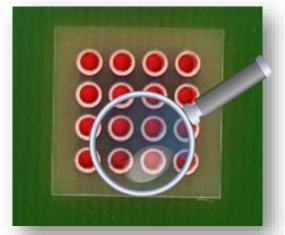
HAL – Hot Air Levelling

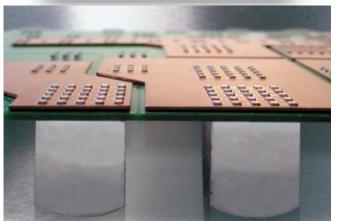




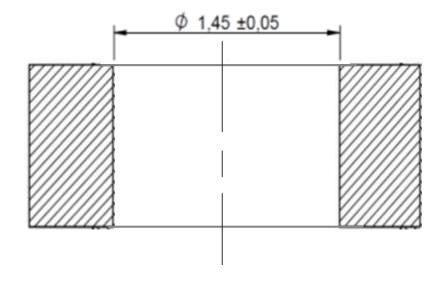


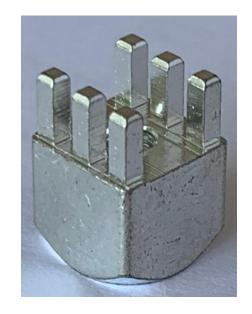


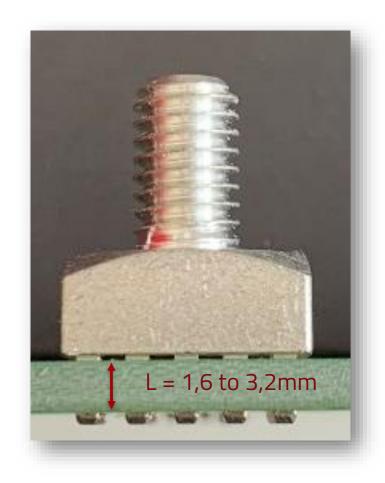


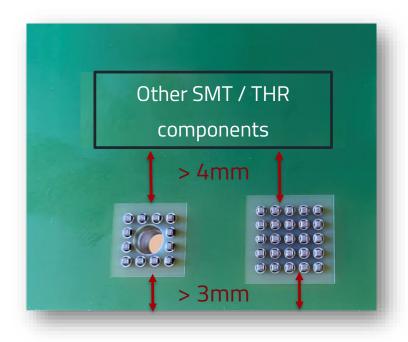


Pure copper bar (Drill hole 1,45 +-0,05)

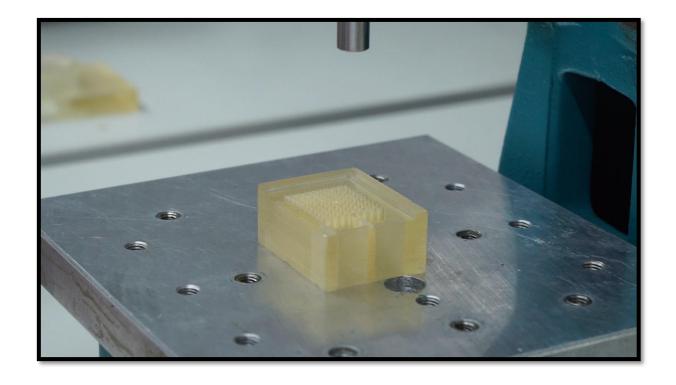








BASIC PROCESS FOR PRESS-FIT



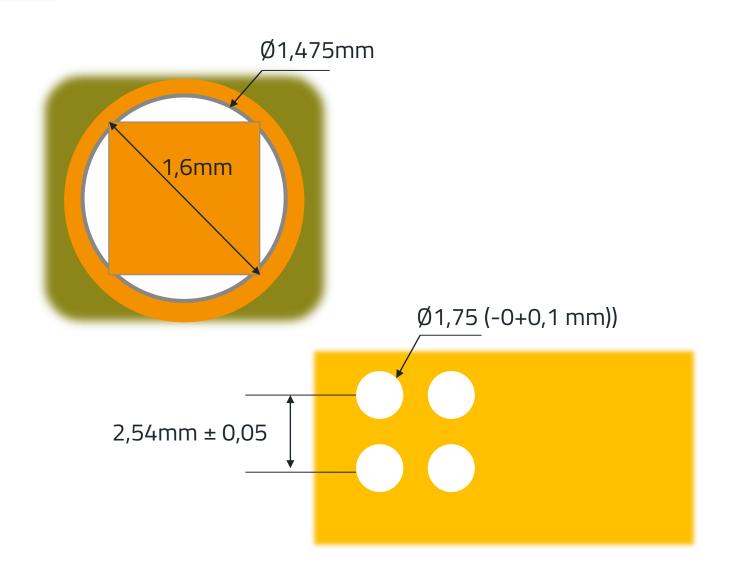


PRESS FIT PROCESS: SUPPORT

Support location

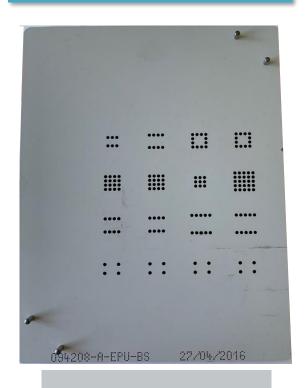


3D printing prototype

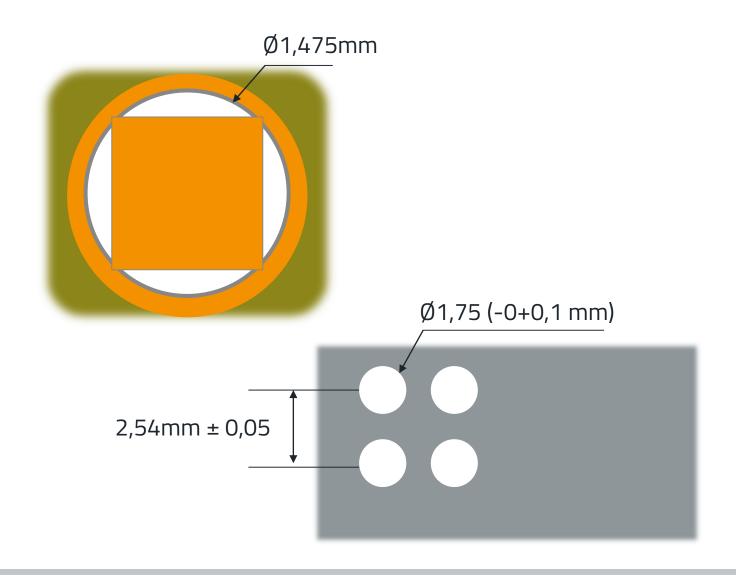


PRESS FIT PROCESS: SUPPORT

Support location



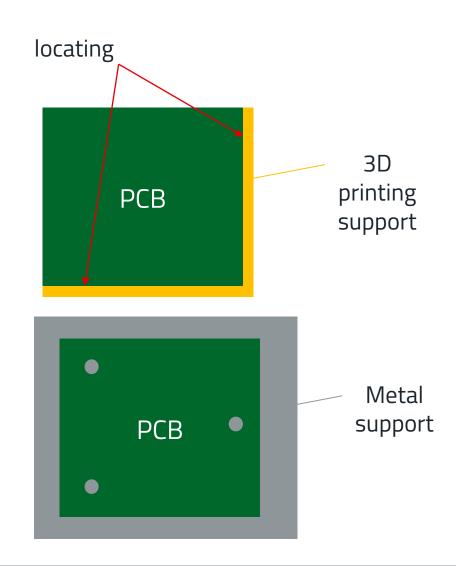
Metal final version



PRESS FIT PROCESS: SUPPORT

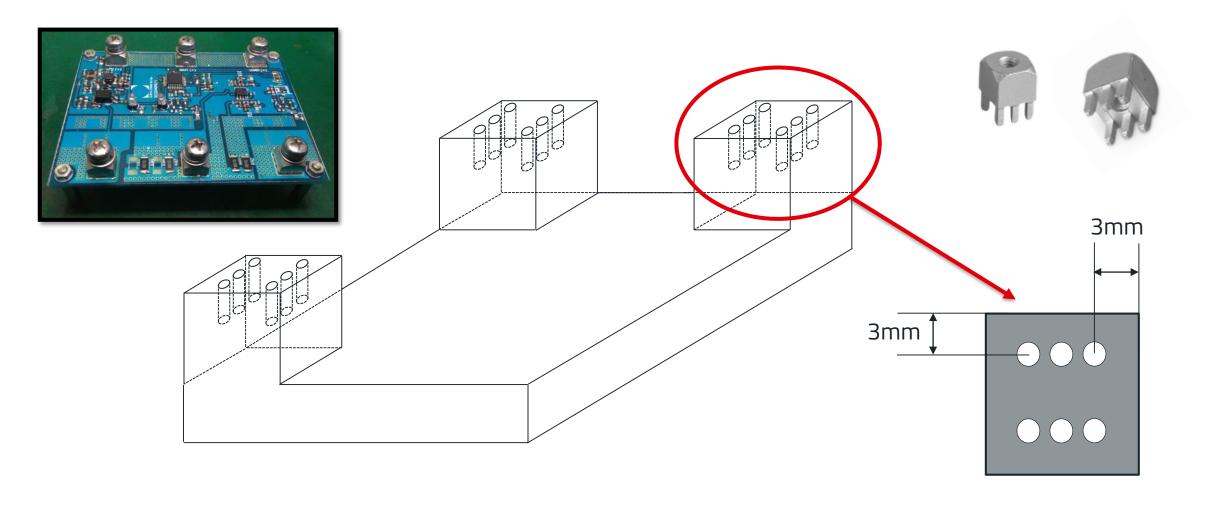
Support locating



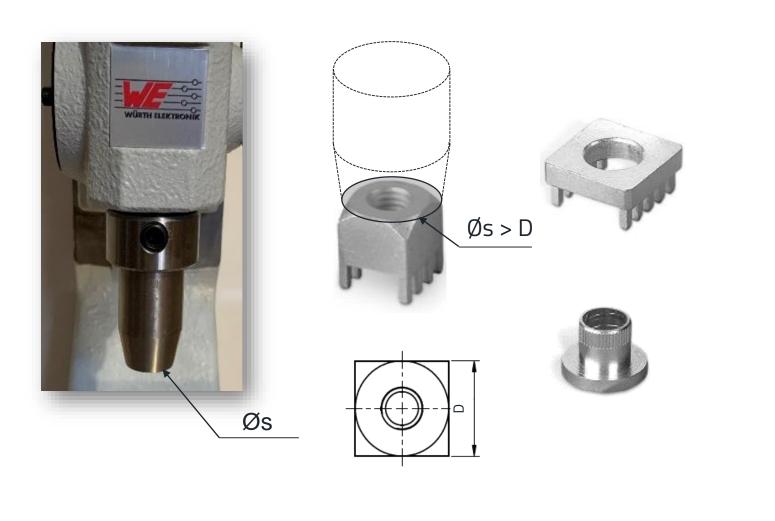


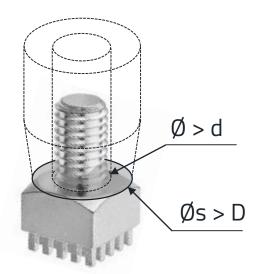


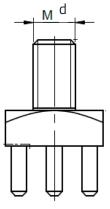
PRESS FIT PROCESS: SUPPORT REAL CASE

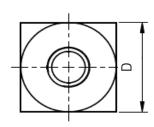


PRESS FIT PROCESS: STAMP





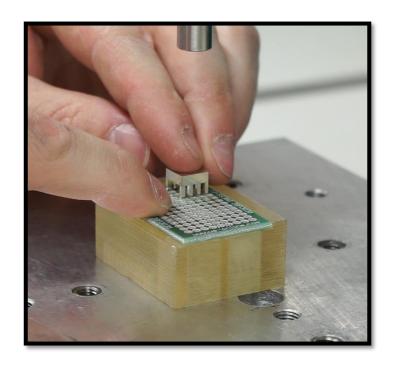


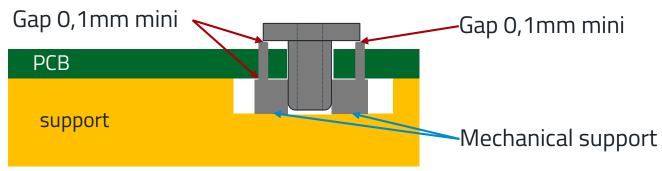


PRESS FIT PROCESS: STAMP



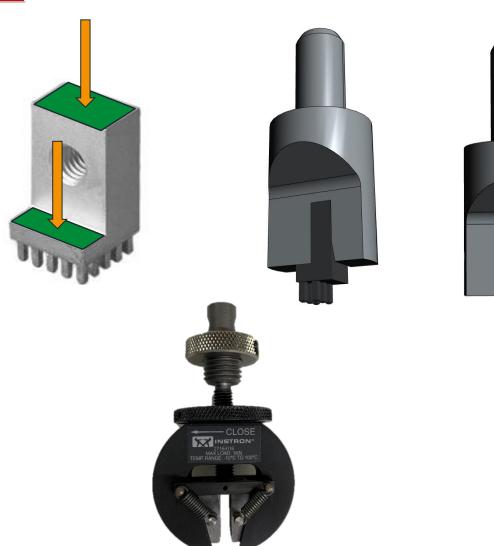






PRESS FIT PROCESS: STAMP







PRESS FIT PROCESS: PRESS

All type of press for REDCUBE

Press Schmidt



Press Gechter

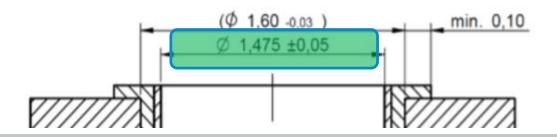




<u>INSERTION FORCE – PRESS DIMENSIONING</u>

PCB thick ness		Empirical press-in PCB insertion force per (N/pin) min / max																		
(mm)	Chemical tin									G			HAL							
(mm)	Ø1,	Ø1,425 Ø1,475		475	Ø1,525			Ø1,425		Ø1,475		Ø1,525			Ø1,40		Ø1,45		Ø1,50	
1,6	120	220	80	160	40	130		140	250	100	200	60	170	1	40	250	100	200	50	170
2,4	170	330	110	240	60	200		200	400	130	300	70	250	2	200	400	130	300	70	250
3,2	220	460	140	340	80	280		260	500	170	420	80	360	2	:60	500	170	420	80	360

Specification for chemical surfaces





<u>INSERTION FORCE – PRESS DIMENSIONING</u>

PCB thick ness		Empirical press-in PCB insertion force per (N/pin) min / max																					
(mm)	Chemical tin ENIG													HAL									
(mm)	Ø1,	Ø1,425		Ø1,475		Ø1,525		Ø1,425		Ø1,475		Ø1,525		Ø1,40		Ø1,45		Ø1,50					
1,6	120	220	80	160	40	130		140	250	100	200	60	170	140	250	100	200	50	170				
2,4	170	330	110	240	60	200		200	400	130	300	70	250	200	400	130	300	70	250				
3,2	220	460	140	340	80	280		260	500	170	420	80	360	260	500	170	420	80	360				



Example: redcube12 pins – PCB chemical tin thickness 3,2mm

 \rightarrow 1,7 kN < press effort < 4 kN



<u>INSERTION FORCE – PRESS DIMENSIONING</u>



Example: redcube 12 pins – PCB chemical tin thickness 3,2mm

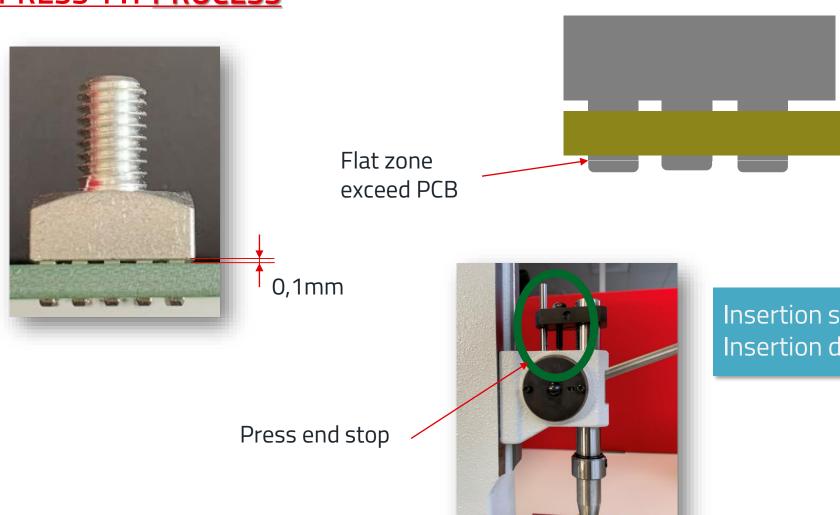
 \rightarrow 1,7 kN < press effort < 4 kN

Press dimensionning > max effort +20% security

Example: press rack and pinion of 5kN.



PRESS-FIT PROCESS



Insertion speed ≈ 100-250mm/mn Insertion done in 1 single time



CRIMPING TOOLS FOR TERMINALS



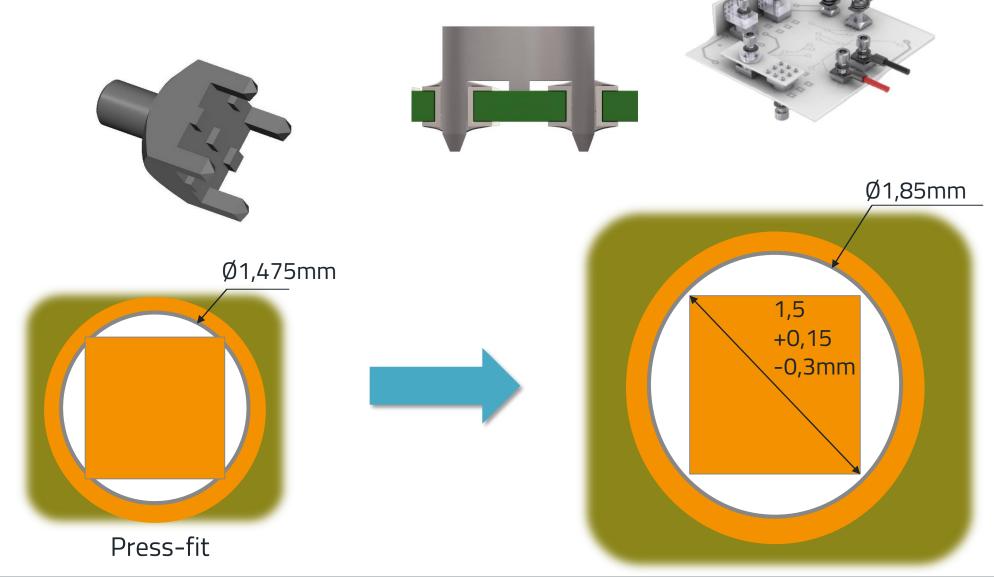


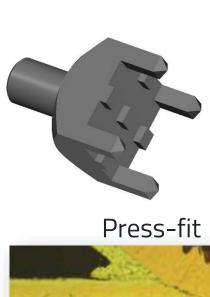




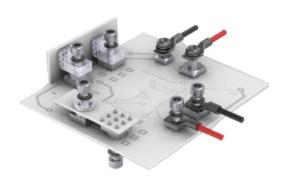


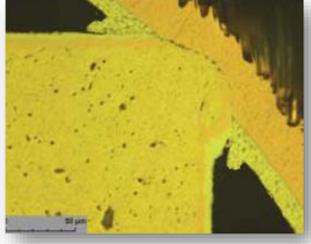










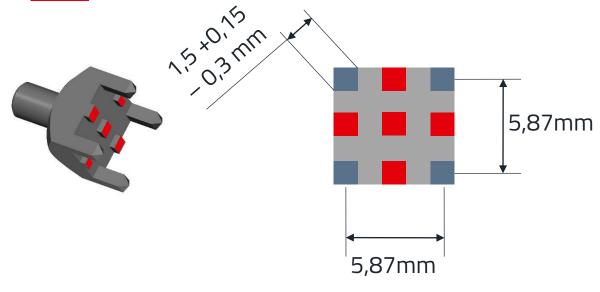


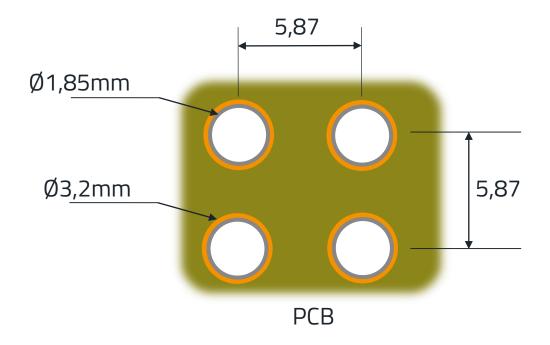


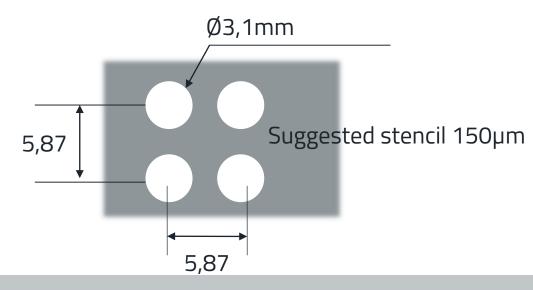
THR

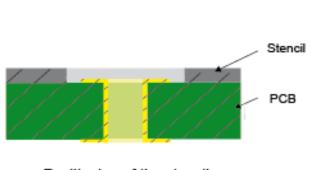
Up to 350A

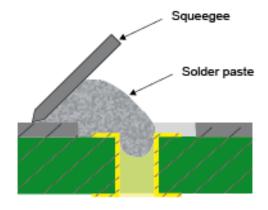
Up to 85A

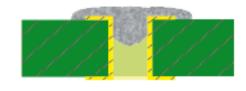








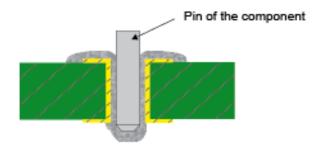


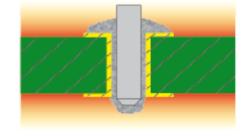


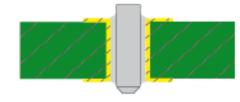
Positioning of the stencil

Applying of the solder paste

Solder paste fills the stencil's aperture





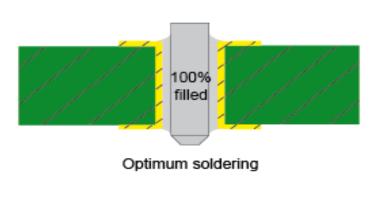


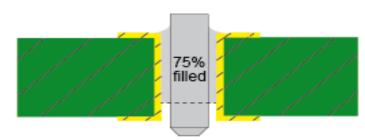
Positioning of the component

Reflow soldering

Component soldered

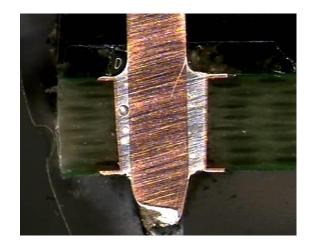
<u>THR</u>

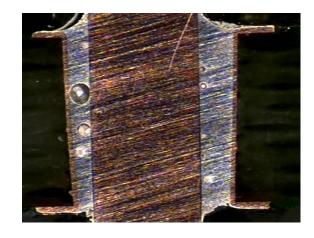




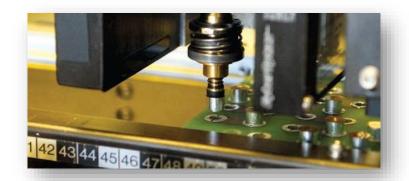
Acceptable soldering







SMT PRINCIPLE



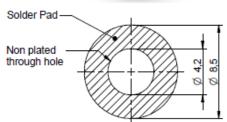




Open thread

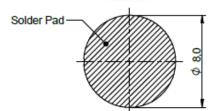
Up to 85A





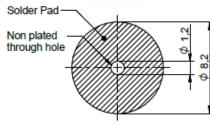
Increase torque



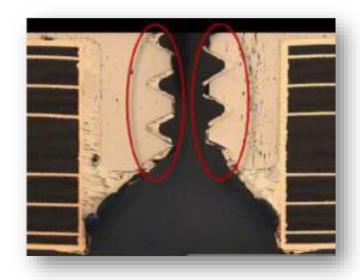


PCB centered





SMT: WHY NOT PLATED THROUGH HOLE

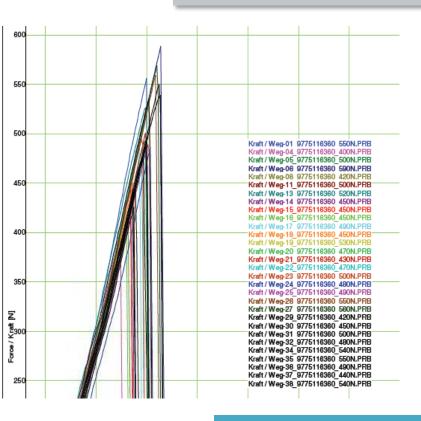






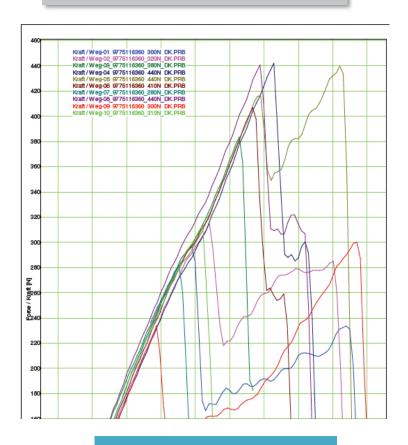
SMT: WHY NOT PLATED THROUGH HOLE

NON plated through hole Shear force



From 490 to 590 N

Plated through hole Shear force

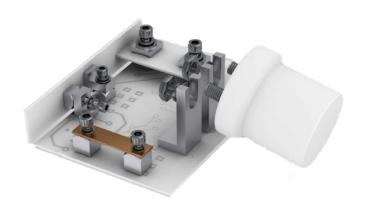


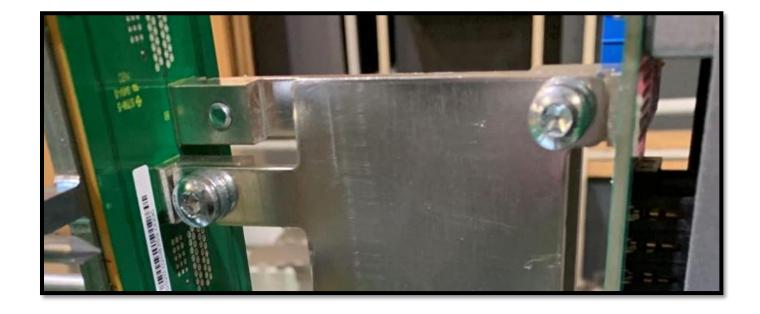
From 280 to 440 N



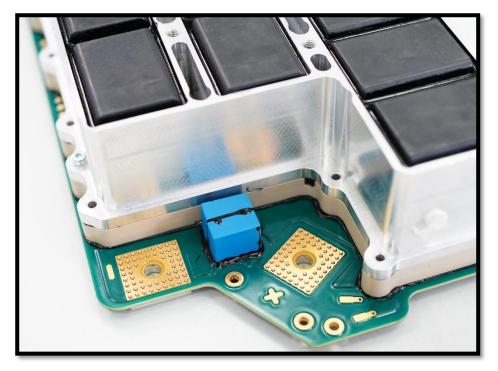
APPLICATIONS: COPPER BAR

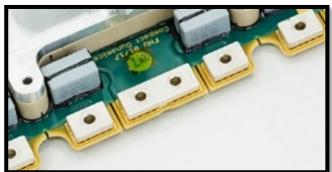




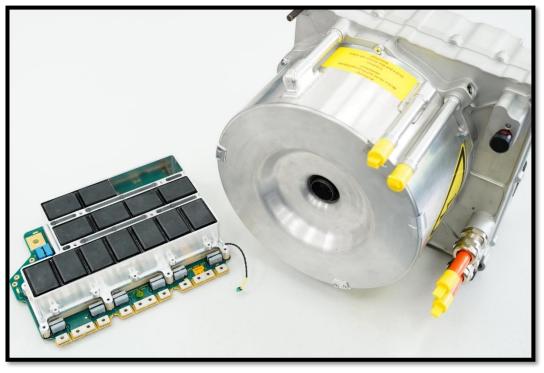


APPLICATIONS: FORMULA-E



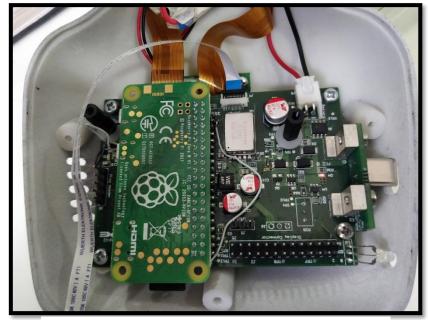






PRESS FIT





Perpendicular board to board



High power backplane



WATER TIGHTNESS POWER BATTERY

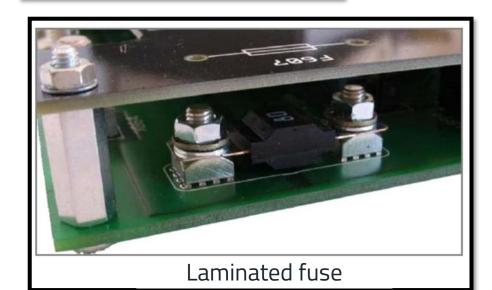


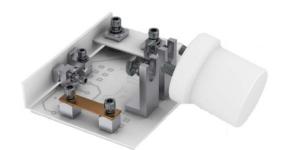


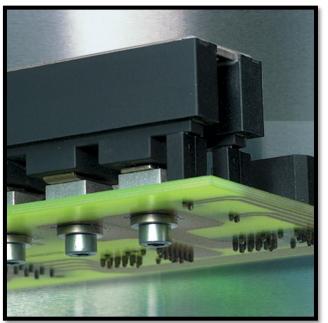


SPECIFIC APPLICATIONS

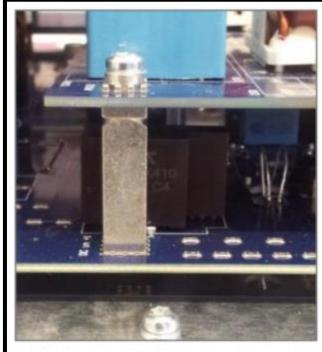








IGBT connection

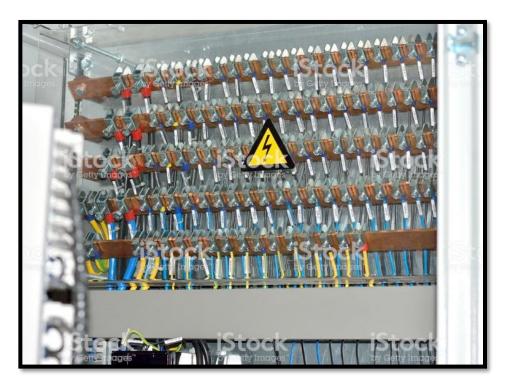


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